

Number of Components: Single  
 Mix Ratio By Weight: N/A  
 Specific Gravity: 1.13  
 Part A  
 Part B  
 Pot Life: 28 Days  
 Shelf Life: One year at -40°C

Minimum Bond Line Cure Schedule\*:  
 180°C 1 Hour

Note: Container(s) should be kept closed when not in use. For filled systems, mix contents of each container (A & B) thoroughly before mixing the two parts together. \*Please see Applications Note available on our website.

### Product Description:

EPO-TEK<sup>®</sup> E3035T-2 is a single component, silver-filled epoxy for semiconductor die attach, as well as SMD attach on hybrid circuits.

### EPO-TEK<sup>®</sup> E3035T-2 Advantages & Application Notes:

- This epoxy can be classified as a higher viscosity version of EPO-TEK<sup>®</sup> E3035, suggested for the following purposes:
  - Used for improved stencil printing via small apertures.
  - Less flow-out between small pads like 0402 or 0603 caps and resistors.
- Performs exceptionally well as a die attach for small chips such as GaAs, LEDs and diodes.
- Capable of resisting 260°C green reflow process, low outgassing in hermetic lid-seal processes near 300°C, and organic burn-in up to 150°C/1000 hours storage.
- Low levels of water extractable monovalent ions such as Chlorides.
- Capable of JEDEC Level II die-attach packaging on die-paddles and lead-frames.
- Widely used epoxy; popular choice for silver-filled epoxies; opto-packaging, hybrids, and many types of substrates including kovar, ceramic and BT
- Contact techserv@epotek.com for your best recommendation. Alternate viscosities and lower curing temperatures are available.

**Typical Properties:** (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 180°C/1 hour ; \* denotes test on lot acceptance basis)

Physical Properties:	
*Color: Silver	Weight Loss:
*Consistency: Thixotropic paste	@ 200°C: 0.15%
*Viscosity (@ 2.5 RPM/23°C): 80,000 – 120,000 cPs	@ 250°C: 0.29%
Thixotropic Index: 4.09	@ 300°C: 0.32%
*Glass Transition Temp.(Tg): ≥ 100°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	Operating Temp:
Coefficient of Thermal Expansion (CTE):	Continuous: - 55°C to 200°C
Below Tg: 42x 10 <sup>-6</sup> in/in/°C	Intermittent: - 55°C to 300°C
Above Tg: 80 x 10 <sup>-6</sup> in/in/°C	Storage Modulus @ 23°C: 369,338 psi
Shore D Hardness: 85	Ions: Cl <sup>-</sup> 62 ppm
Lap Shear Strength @ 23°C: 1,776 psi	Na <sup>+</sup> 21 ppm
Die Shear Strength @ 23°C: ≥ 10 Kg / 3,400 psi	NH <sub>4</sub> <sup>+</sup> 24 ppm
Degradation Temp. (TGA): 390°C	K <sup>+</sup> 3 ppm
	*Particle Size: ≤ 20 Microns
Electrical Properties:	
*Volume Resistivity @ 23°C: ≤ 0.0005 Ohm-cm	
Thermal Properties:	
Thermal Conductivity: 1.44 W/mK	

### EPOXY TECHNOLOGY, INC.

14 Fortune Drive, Billerica, MA 01821-3972 Phone: 978.667.3805 Fax: 978.663.9782

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